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Sheet 1 of 1

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| Form PTO-1449 (REV. 8-83) | | US Dept. of Commerce PATENT & TRADEMARK OFFICE | | ATTY DOCKET NO. 105895 | | APPLICATION NO. 09/509,669 | |
| INFORMATION DISCLOSURE STATEMENT (Use several sheets if necessary) | | | | APPLICANT(S) Akihiro MURATA et al. | | | |
| | | | | FILING DATE April 4, 2000 | | GROUP 2872 | |
| U.S. PATENT DOCUMENTS | | | | | | | |
| EXAMINER INITIAL | | DOCUMENT NUMBER | DATE | NAME | CLASS | SUB CLASS | |
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| EXAMINER | | | | DATE CONSIDERED | | | |
| <i>Alexander V. Aron</i> | | | | 1/8/03 | | | |
| Examiner: Initial if citation considered, whether or not citation is in conformance with M.P.E.P. 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. | | | | | | | |